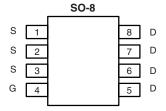




N-Channel 30-V (D-S) MOSFET with Schottky Diode

MOSFET PRODUCT SUMMARY					
V _{DS} (V)	I _D (A)				
30	0.016 at V _{GS} = 10 V	9.5			
	0.021 at V _{GS} = 4.5 V	7.7			

SCHOTTKY PRODUCT SUMMARY					
V _{DS} (V)	V _{SD} (V) Diode Forward Voltage	I _F (A)			
30	0.50 V at 1.0 A	1.4			



Top View

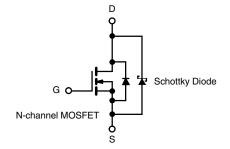
Ordering Information: Si4812BDY-T1-E3 (Lead (Pb)-free)

Si4812BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)

FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- LITTLE FOOT® Plus Power MOSFET
- 100 % R_g Tested





ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted						
Parameter		Limit		mit		
		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage (MOSFET)	Drain-Source Voltage (MOSFET)		30			
Reverse Voltage (Schottky)		V _{DS}	30		V	
Gate-Source Voltage (MOSFET)	V_{GS}	± 20				
Continuous Drain Current (T. – 150 °C) (MOSEET)	$T_A = 25 ^{\circ}C$	9.5		7.3		
Continuous Drain Current ($T_J = 150$ °C) (MOSFET) ^{a, b} $T_A = 7$			7.7	5.9		
Pulsed Drain Current (MOSFET)	I _{DM}	50				
Continuous Source Current (MOSFET Diode Condu	I _S	2.1	1.2	А		
Average Forward Current (Schottky)	I _F	1.4	0.8			
Pulsed Forward Current (Schottky)	I _{FM}	30				
Single Pulse Avalanche Current Avalanche Energy L = 0.1 mH		I _{AS}	5 1.25			
		E _{AS}			mJ	
Maximum Power Dissipation (MOSFET) ^{a, b}	T _A = 25 °C	P _D	2.5	1.4	W	
waximum Power Dissipation (MOSFET)**	T _A = 70 °C		1.6	0.9		
Maximum Power Dissipation (Schottky) ^{a, b}	T _A = 25 °C		2.0	1.2		
waximum Power Dissipation (Schottky)	T _A = 70 °C		1.3	0.8		
Operating Junction and Storage Temperature Rang	T _J , T _{stg}	- 55 t	o 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter	Device	Symbol	Typical	Maximum	Unit	
	MOSFET	R _{thJA}	40	50		
Maximum Junction-to-Ambient (t ≤ 10 s) ^a	Schottky		50	60	1	
M : 1 : 1 : 1 A 1 : 1 (1 O 1 O 1 O 1	MOSFET		72	90	°C/W	
Maximum Junction-to-Ambient (t = Steady State) ^a	Schottky		85	100	- C/VV	
Manipulation to Foot (1. Objects Objects)	MOSFET	R _{thJF}	18	23	1	
Maximum Junction-to-Foot (t = Steady State) ^a	Schottky		24	30		

Notes:

a. Surface Mounted on FR4 board.

 $b.\ t \leq 10\ s.$

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MOSFET AND SCHOTTKY SPECIFICATIONS T _J = 25 °C, unless otherwise noted								
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1		3	V		
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA		
		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$		0.004	0.100	mA		
Zero Gate Voltage Drain Current (MOSFET and Schottky)	I _{DSS}	V_{DS} = 30 V, V_{GS} = 0 V, T_{J} = 100 °C		0.7	10			
(MOST ET and Solicitity)		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 125 °C		3.0	20			
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	20			Α		
D : 0	D	V _{GS} = 10 V, I _D = 9.5 A		0.013	0.016	-		
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 7.7 \text{ A}$		0.0165	0.021	Ω		
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 9.5 A		45		S		
	V	I _S = 1.0 A, V _{GS} = 0 V		0.45	0.50	V		
Schottky Diode Forward Voltage ^a	V _{SD}	I _S = 1.0 A, V _{GS} = 0 V, T _J = 125 °C		0.33	0.42			
Dynamic ^b								
Total Gate Charge	Qg			8.5	13			
Gate-Source Charge	Q _{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 9.5 \text{ A}$		3		nC		
Gate-Drain Charge	Q_{gd}			2.6				
Gate Resistance	R _g		0.3	0.7	1.1	Ω		
Turn-On Delay Time	t _{d(on)}			15	25			
Rise Time	t _r	$V_{DD} = 15 \text{ V}, R_L = 15 \Omega$		13	20			
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ 1 A, V_{GEN} = 10 V, R_g = 6 Ω		20	30	ns		
Fall Time	t _f			8	15			
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 1.0 A, dl/dt = 100 A/μs		22	35			

Notes:

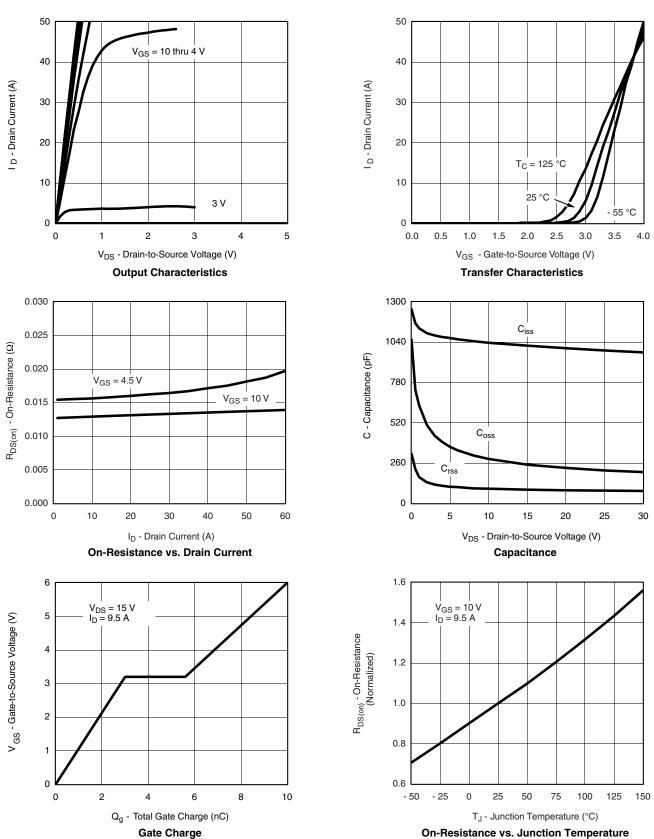
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.



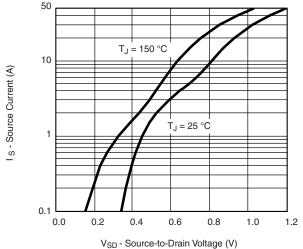
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



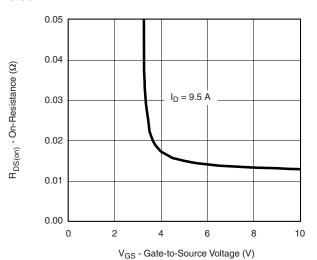
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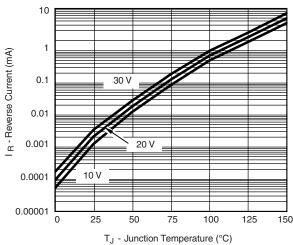
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



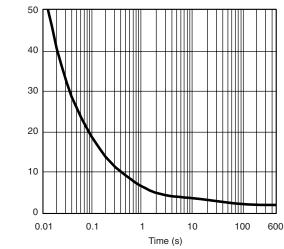
Source-Drain Diode Forward Voltage



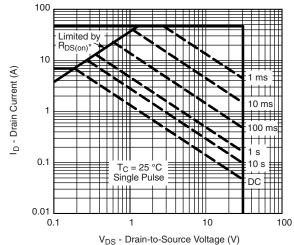
On-Resistance vs. Gate-to-Source Voltage



Reverse Current (Schottky)



Single Pulse Power (MOSFET)



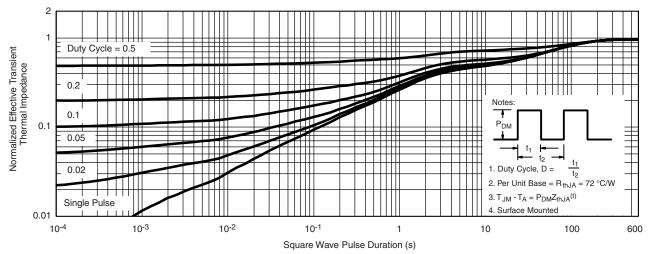
Power (W)

* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

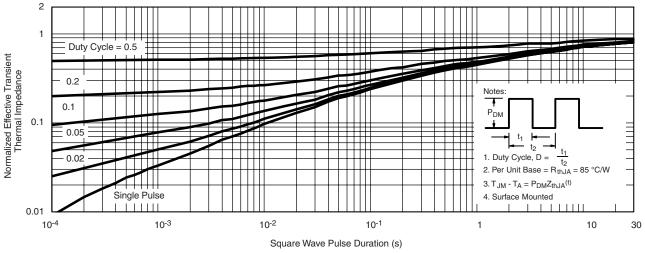
Safe Operating Area, Junction-to-Case



TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient (MOSFET)



Normalized Thermal Transient Impedance, Junction-to-Ambient (Schottky)

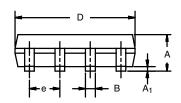
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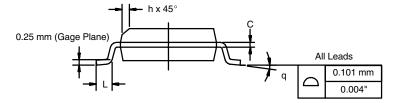
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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES		
DIM	Min	Max	Min	Max	
Α	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
ECN: C-06527-Rev. I. 11-Sep-06					

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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